L Number	Hits	Search Text	DB	Time stamp
1	9417	(chip or ic or die or module or component) near3 (positioning or position or positioned or locating or located or aligning or alignment or aligned or align) near3 (template or aperture or socket or guide or recess)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 14:47
2	278	(chip or ic or die or module or component) near3 (positioning or position or positioned or aligning or alignment or aligned or align) near3 (template)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 13:43
3	99	(chip or ic or die) near3 (positioning or position or positioned or aligning or alignment or aligned or align) near3 (template)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 13:43
4	146	(chip or ic or die) near5 (positioning or position or positioned or aligning or alignment or aligned or align) near3 (template)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 14:04
5	9	5561328.URPN.	USPAT	2004/02/18 13:59
6	1115	(chip or ic or die) near5 (positioning or position or positioned or aligning or alignment or aligned or align) near3 (aperture)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 14:05
7	392	(chip or ic or die) near5 (positioning or position or positioned or aligning or alignment or aligned or align) near3 (aperture) and (silicon or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 14:05
8	141	(chip or ic or die) near2 (aperture) near3 (positioning or position or positioned or aligning or alignment or aligned or align) and (silicon or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 14:10
9	130	(chip or ic or die) near5 (mounting or mounted or bonding or bonded or flip adj chip or packaging) near3 (alignment or placement or aligning or aligned) near4 (precise or precision or precisely or exact or exactly)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 14:18
10	19	(chip or ic or die) near5 (mounting or mounted or bonding or bonded or flip adj chip or packaging) near3 (alignment or placement or aligning or aligned) near4 (sidewall or wall)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 14:20
11	2703	(chip or ic or die) near3 (receiving or received or inserting or insertion or inserted or holding or aligning or alignment) near2 (recess or slot or aperture)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 14:24
12	1664	(chip or ic or die) near3 (receiving or received or inserting or insertion) near2 (recess or slot or aperture)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 14:24
13	106	(chip or ic or die) near3 (receiving or received or inserting or insertion) near2 (recess or slot or aperture) near6 (template or self-aligned or self-alignment or walls or guide or sidewall or ramp)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 14:28
14	2	5824186.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 14:32
15	2	("4990462" | "5091045").PN.	USPAT	2004/02/18 14:28
16	19	5824186.URPN.	USPAT	2004/02/18 14:28

17	326	(optical) near4 (module or component or ic or chip or die) near5 (array or matrix) near5 (alignment or aligning or aligned or positioning or placement or positioned)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 14:43
18	394	(chip or ic or die) near2 (self-alignment or self-aligning or self-aligned)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 14:43
19	25	(chip or ic or die) near2 (self-alignment or self-aligning or self-aligned) near5 (aperture or recess or slot or socket or opening or depression)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 14:44
20	26	(chip or ic or die) near2 (self-alignment or self-aligning or self-aligned) near5 (aperture or recess or slot or socket or opening or depression or wall or sidewall)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 14:44
21	395	(chip or ic or die or module or component) near3 (positioning or position or positioned or locating or located or aligning or alignment or aligned or align) near3 (template or aperture or socket or guide or recess) and (template or aperture or socket or guide or recess) near3 (metal or epitaxial)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 14:46
22	30	(chip or ic or die or module or component) near3 (positioning or position or positioned or locating or located or aligning or alignment or aligned or align) near3 (template or guide or wall or sidewall) near3 (metal or epitaxial or aluminum or titanium or tungsten or nickel or chromium)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 14:49